

V_{SM}	=	2800 V
I_{TAVM}	=	2430 A
I_{TRMS}	=	3820 A
I_{TSM}	=	43000 A
V_{TO}	=	0.85 V
r_T	=	0.160 mΩ

Bi-Directional Control Thyristor

5STB 24N2800

Doc. No. 5SYA1041-03 Sep. 01

- Two thyristors integrated into one wafer
- Patented free-floating silicon technology
- Designed for traction, energy and industrial applications
- Optimum power handling capability
- Interdigitated amplifying gate.

The electrical and thermal data are valid for one thyristor half of the device.

Blocking

Part Number	5STB 24N2800	5STB 24N2600	5STB 24N2200	Conditions
V_{SM}	3000 V	2800 V	2400 V	$f = 5 \text{ Hz}, t_p = 10\text{ms}$
V_{RM}	2800 V	2600 V	2200 V	$f = 50 \text{ Hz}, t_p = 10\text{ms}$
I_{SM}	$\leq 400 \text{ mA}$			V_{SM}
I_{RM}	$\leq 400 \text{ mA}$			V_{RM}
dV/dt_{crit}	1000 V/ μ s @ Exp. to 0.67 \times V_{SM}			$T_j = 125^\circ\text{C}$

V_{RM} is equal to V_{SM} up to $T_j = 110^\circ\text{C}$

Mechanical data

F_M	Mounting force	nom.	90 kN
		min.	81 kN
		max.	108 kN
a	Acceleration Device unclamped		50 m/s ²
	Device clamped		100 m/s ²
m	Weight		2.9 kg
D _S	Surface creepage distance		53 mm
D _a	Air strike distance		22 mm

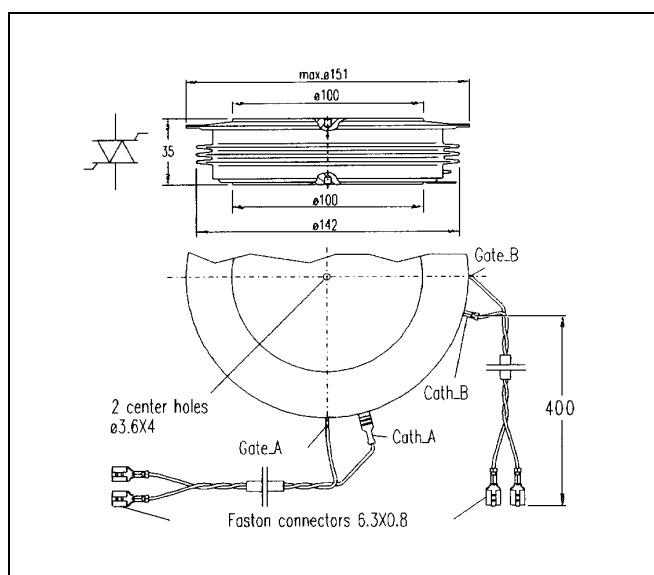


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On-state

I_{TAVM}	Max. average on-state	2430 A	Half sine wave, $T_C = 70^\circ\text{C}$	
I_{TRMS}	Max. RMS on-state current	3820 A		
I_{TSM}	Max. peak non-repetitive surge current	43000 A	$tp = 10 \text{ ms}$	$T_j = 125^\circ\text{C}$ After surge: $V_D = V_R = 0\text{V}$
		46000 A	$tp = 8.3 \text{ ms}$	
I^2t	Limiting load integral	9245 kA ² s	$tp = 10 \text{ ms}$	$V_D = V_R = 0\text{V}$
		8781 kA ² s	$tp = 8.3 \text{ ms}$	
V_T	On-state voltage	1.35 V	$I_T = 3000 \text{ A}$	$T_j = 125^\circ\text{C}$
V_{TO}	Threshold voltage	0.85 V	$I_T = 1500 - 4500 \text{ A}$	
r_T	Slope resistance	0.160 mΩ		
I_H	Holding current	50-250 mA	$T_j = 25^\circ\text{C}$	
		25-150 mA	$T_j = 125^\circ\text{C}$	
I_L	Latching current	100-500 mA	$T_j = 25^\circ\text{C}$	
		50-300 mA	$T_j = 125^\circ\text{C}$	

Switching

di/dt_{crit}	Critical rate of rise of on-state current	250 A/μs	Cont. f = 50 Hz	$V_D \leq 0.67 \cdot V_{DRM}, T_j = 125^\circ\text{C}$
		500 A/μs	60 sec. f = 50Hz	$I_{TRM} = 3000 \text{ A}$ $I_{FG} = 2 \text{ A}, t_r = 0.5 \mu\text{s}$
t_d	Delay time	$\leq 3.0 \mu\text{s}$	$V_D = 0.4 \cdot V_{DRM}$	$I_{FG} = 2 \text{ A}, t_r = 0.5 \mu\text{s}$
t_q	Turn-off time	$\leq 400 \mu\text{s}$	$V_D \leq 0.67 \cdot V_{DRM}$ $dv_D/dt = 20\text{V}/\mu\text{s}$	$I_{TRM} = 3000 \text{ A}, T_j = 125^\circ\text{C}$ $V_R > 200 \text{ V}, di_T/dt = -1.5 \text{ A}/\mu\text{s}$
Q_{fr}	Recovery charge	min	1100 μAs	
		max	2000 μAs	

Triggering

V_{GT}	Gate trigger voltage	$\leq 2.6 \text{ V}$	$T_j = 25^\circ\text{C}$
I_{GT}	Gate trigger current	$\leq 400 \text{ mA}$	$T_j = 25^\circ\text{C}$
V_{GD}	Gate non-trigger voltage	$\geq 0.3 \text{ V}$	$V_D = 0.4 \cdot V_{RM} \quad T_j = 125^\circ\text{C}$
I_{GD}	Gate non-trigger current	$\geq 10 \text{ mA}$	$V_D = 0.4 \cdot V_{RM} \quad T_j = 125^\circ\text{C}$
V_{FGM}	Peak forward gate voltage	12 V	
I_{FGM}	Peak forward gate current	10 A	
V_{RGM}	Peak reverse gate voltage	10 V	
P_G	Maximum gate power loss	3 W	

Thermal

T_j	Operating junction temperature range	-40...125 °C	Anode side cooled
T_{stg}	Storage temperature range	-40...150 °C	
R_{thJC}	Thermal resistance junction to case	22.8 K/kW	
		22.8 K/kW	Cathode side cooled
R_{thCH}	Thermal resistance case to heat sink	11.4 K/kW	Double side cooled
		4 K/kW	Single side cooled
		2 K/kW	Double side cooled

Analytical function for transient thermal impedance:

$$Z_{thJC}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
$R_i(K/kW)$	6.77	2.51	1.34	0.78
$\tau_i(s)$	0.8651	0.1558	0.0212	0.0075

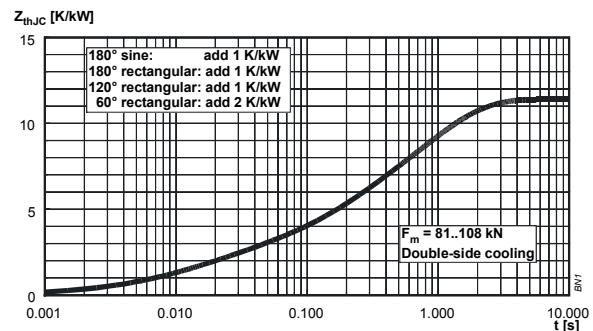


Fig. 1 Transient thermal impedance junction to case.

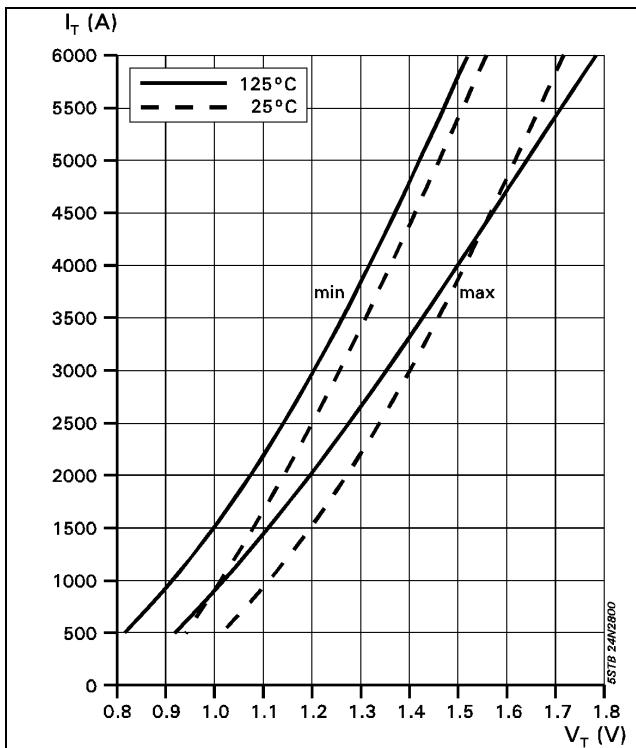


Fig. 2 On-state characteristics.

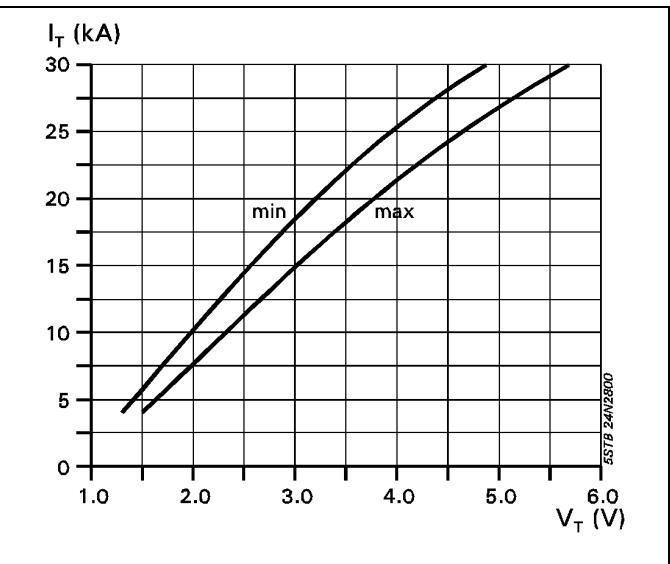


Fig. 3 On-state characteristics.

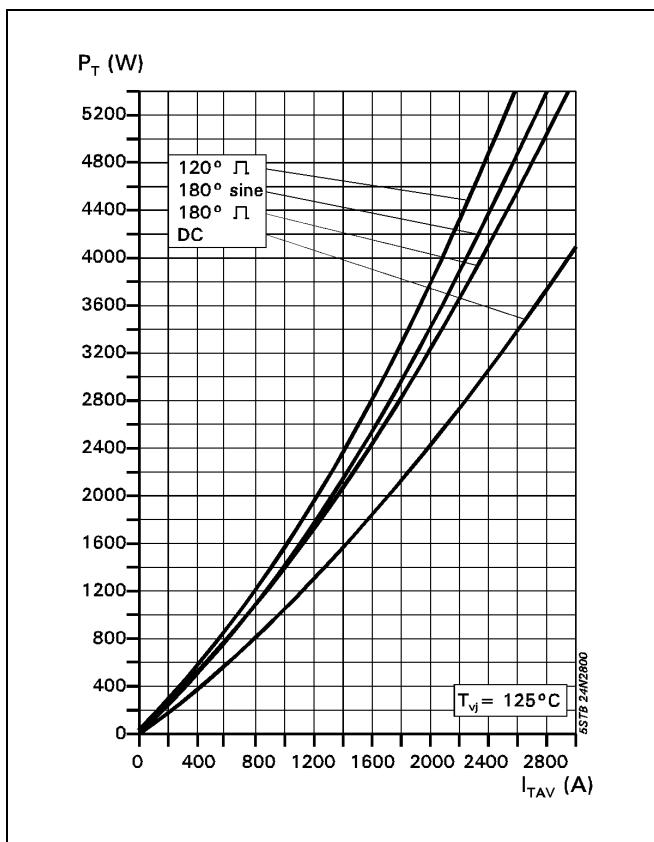


Fig. 4 On-state power dissipation vs. mean on-state current. Turn - on losses excluded.

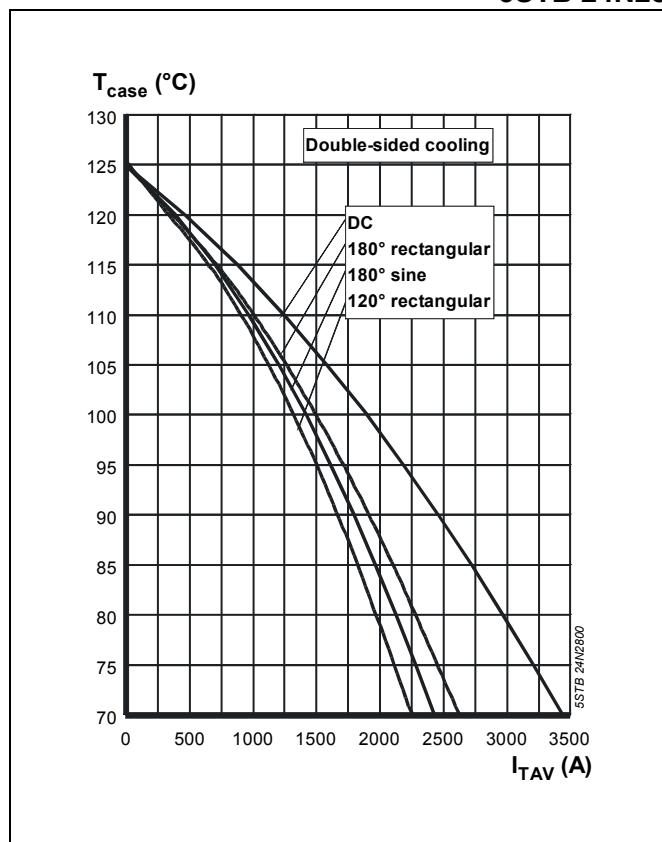


Fig. 5 Max. permissible case temperature vs. mean on-state current.

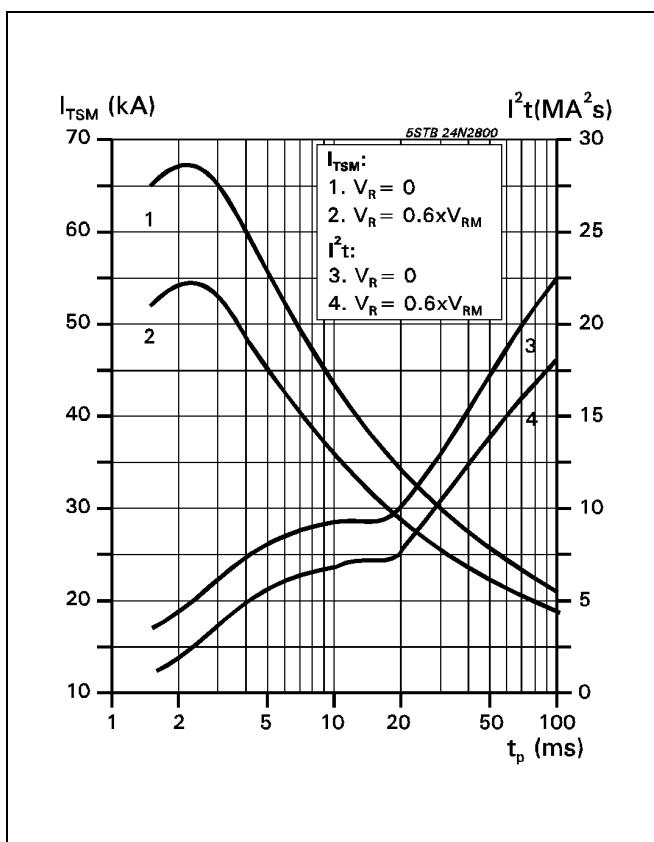


Fig. 6 Surge on-state current vs. pulse length. Half-sine wave.

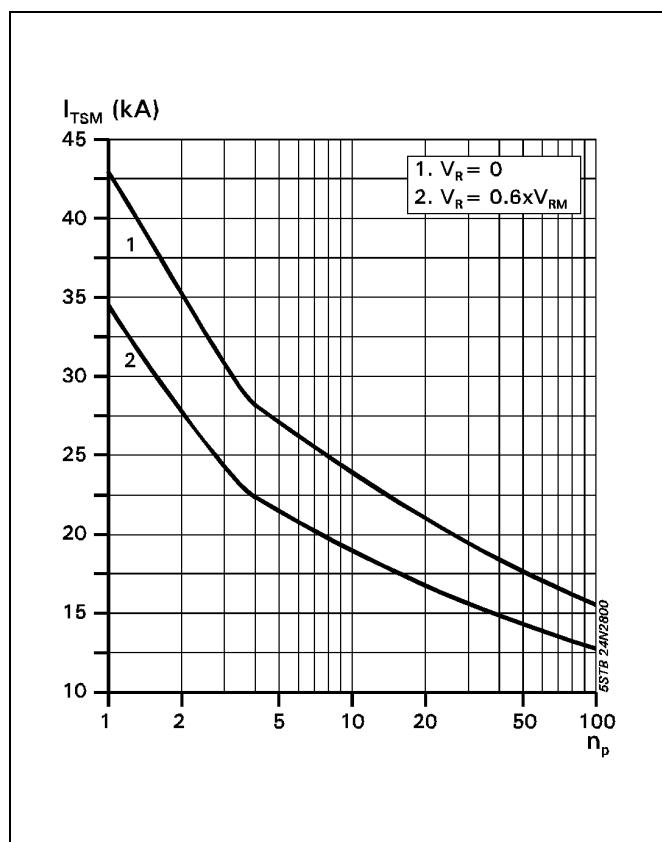


Fig. 7 Surge on-state current vs. number of pulses. Half-sine wave, 10 ms, 50Hz.

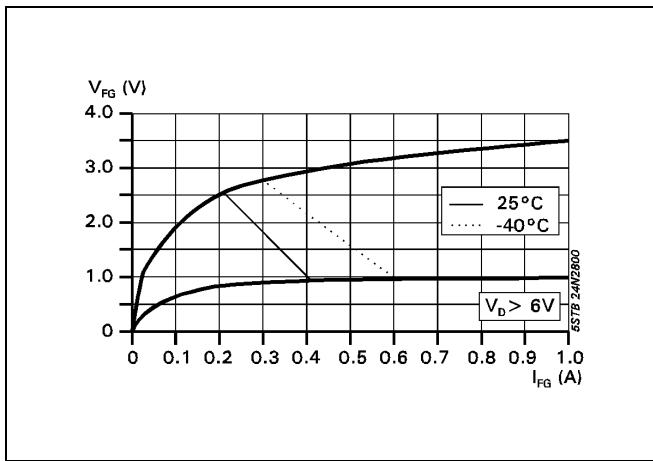


Fig. 8 Gate trigger characteristics.

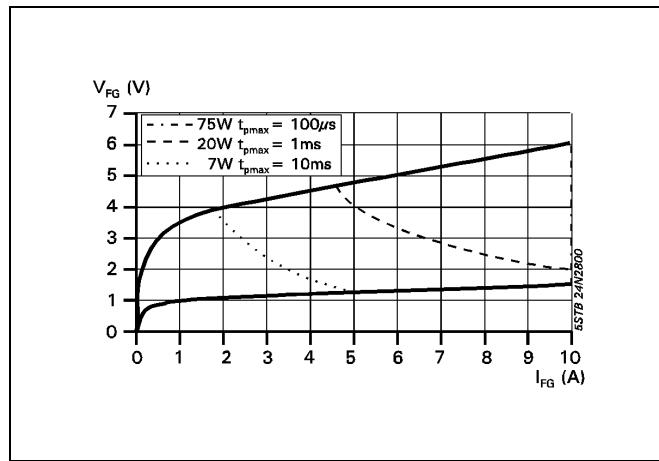


Fig. 9 Max. peak gate power loss.

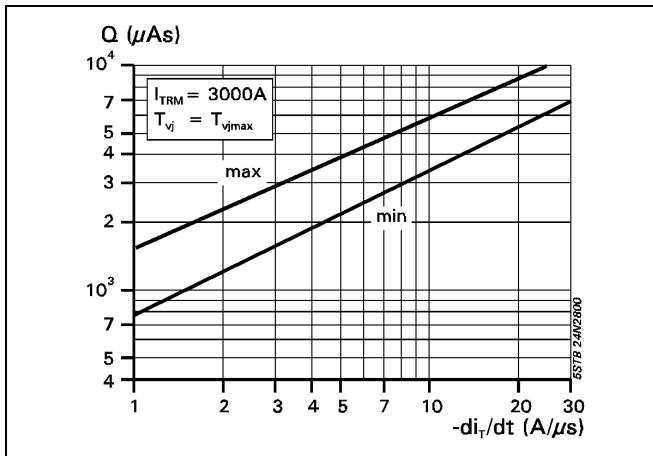


Fig. 10 Recovery charge vs. decay rate of on-state current.

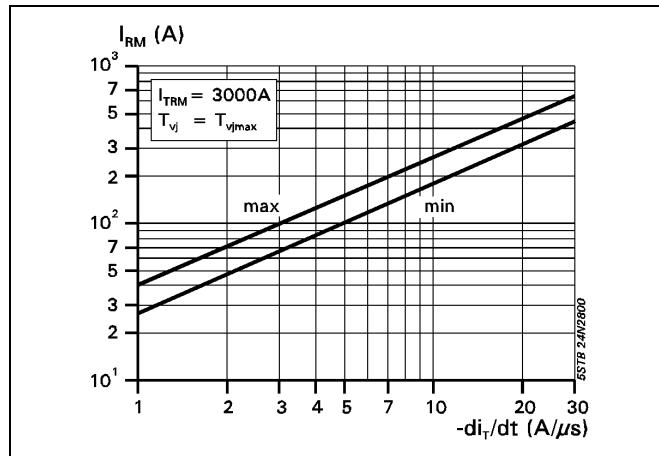


Fig. 11 Peak reverse recovery current vs. decay rate of on-state current.

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ABB Semiconductors AG

Fabrikstrasse 3
CH-5600 Lenzburg, Switzerland

Telephone +41 (0)62 888 6419
Fax +41 (0)62 888 6306
Email abbsem@ch.abb.com
Internet www.abbsem.com

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